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(54) **Title:** DUAL-POLARIZED MAGNETO-ELECTRIC ANTENNA ARRAY

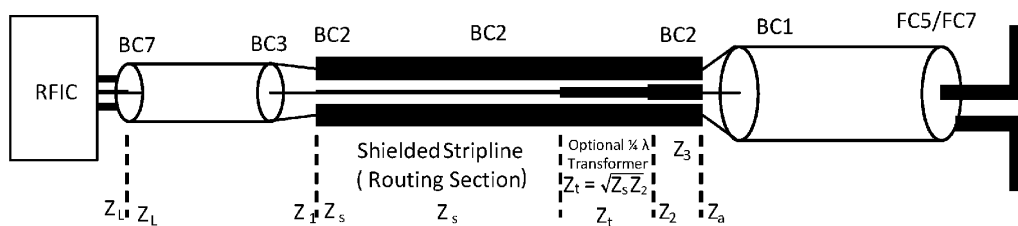


FIG. 8

(57) **Abstract:** A package structure is provided that includes a planar core structure comprising a first side and a second side opposite the first side. The package structure also includes an antenna structure disposed on the first side of the planar core structure. The antenna structure comprises a plurality of first laminated layers, each first laminated layer comprising a first patterned conductive layer formed on a first insulating layer, an antenna formed on one or more first patterned conductive layers of the first laminated layers, the antenna including at least one L-shaped structure. The package structure also includes an interface structure disposed on the second side of the planar core structure, and an antenna feed line structure formed in, and routed through, the interface structure and the planar core structure, wherein the antenna feed line structure is not connected to the planar antenna.



WO 2022/172079 A1